

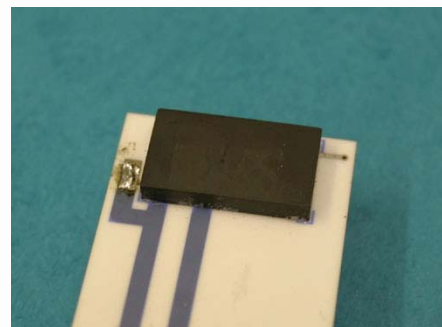
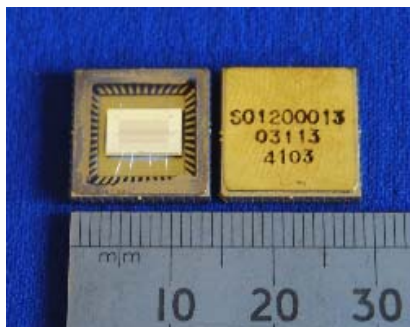
## Data collection/ collation on the “state of the art” in Inertial Microsystems Packaging

### Objective

WP4 have divided the Microsystems field into applications areas (inertial MEMS, environmental MEMS, RF MEM, MOEMS, BioMEMS and Microfluidics).

For each application area a technical working group has been formed to compile state of the art, know-how and capability information, on **Microsystems packaging solutions** (packaging, assembly, interfacing and interconnection), including

- Failure mechanisms of microsystems packaging
- Test structures for packaging monitoring and package design
- Data on packaging construction and materials
- Packaging capabilities within PATENT, and externally within Europe



Pictures courtesy of QinetiQ

### Partners involved

QinetiQ, BUTE

### Summary of results

Collection/ collation of data on packaging of inertial microsystems, accelerometers, g-switches, gyroscopes and magnetometers.

### Offer to industry

Reports and consultancy on packaging of inertial microsystem devices

### Contact

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### Project status

Ongoing